SPC TECHNOLOGY

SPC-F005.DWG

REVISIONS

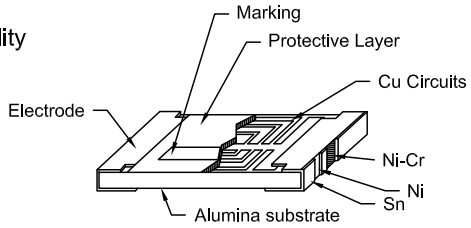
DOC. NO. SPC-F005 * Effective: 7/8/02 * DCP No: 1398

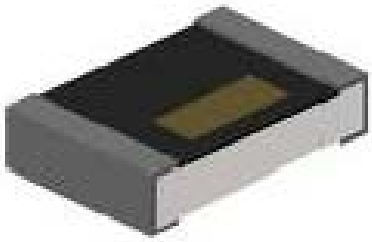
DCP #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE
2048	A	RELEASED	JN	05/21/09	JWM	05/21/09	JWM	05/21/09

Features

- Photolithographic single layer ceramic chip
- High SRF, excellent Q, superior temperature stability
- Tight tolerance of ± 1% or ± 0.1nH
- Self resonant frequency controlled within 10%
- Stable inductance in high frequency circuit
- Highly stable design for critical needs

RoHS Compliant

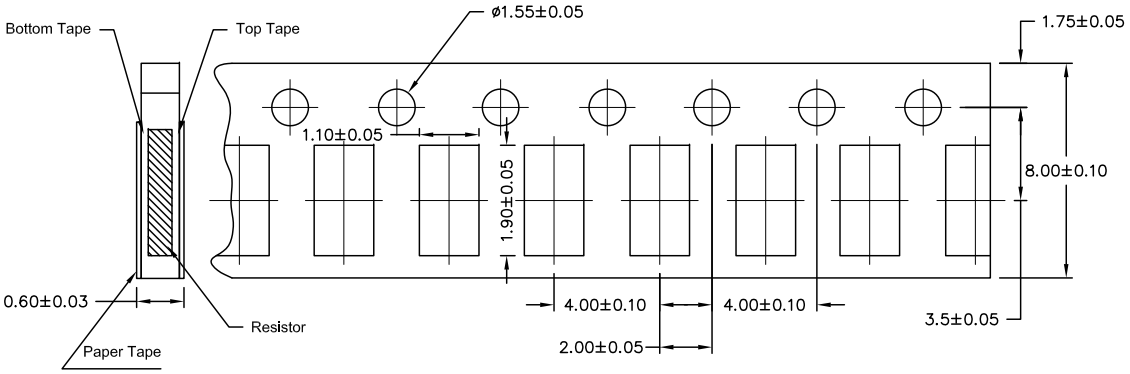


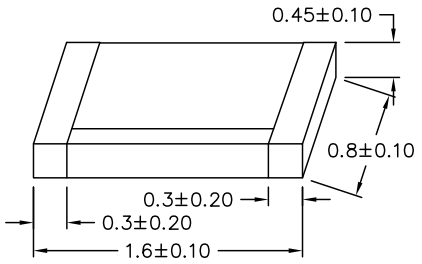


Application

-Cellular Phone, Pagers and GPS Products
-VCO, TCXO, Circuit an dRF Transceiver Module
-Wireless LAN Bluetooth module, Communication Appliances

Tape Dimension





DISCLAIMER:
ALL STATEMENTS AND TECHNICAL INFORMATION CONTAINED HEREIN ARE BASED UPON INFORMATION AND/OR TESTS WE BELIEVE TO BE ACCURATE AND RELIABLE. SINCE CONDITIONS OF USE ARE BEYOND OUR CONTROL, THE USER SHALL DETERMINE THE SUITABILITY OF THE PRODUCT FOR THE INTENDED USE AND ASSUME ALL RISK AND LIABILITY WHATSOEVER IN CONNECTION THEREWITH.

TOLERANCES:

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE FOR REFERENCE PURPOSES ONLY.

DRAWN BY:	DATE:
Jason Nash	05/21/09
CHECKED BY:	DATE:
JWM	05/21/09
APPROVED BY:	DATE:
JWM	05/21/09

DRAWING TITLE: Thin Film Chip Inductor – Case size 0603

SIZE	DWG. NO.	ELECTRONIC FILE	REV
A	Ta-1128	Ta-1128.DWG	A

SCALE: NTS | U.O.M.: Millimeters | SHEET: 1 OF 2

RoHS Compliant

Item		Specification	Test Method
1	Bending Test	As SPEC.	JIS-C-5202-6.1.4 Bending Amplitude 3mm for 10 seconds
2	Dielectric Withstand Voltage	>100V	MIL-STD-202F Method 301. Apply 100VA (rms) for 1minute.
3	Insulation Resistance	>1000MΩ	MIL-STD-202F Method 302 Apply 100VDC for 1minute.
4	Resistance to Soldering Heat	△L<10%	MIL-STD-202F Method 210E 260±5°C, 10±1seconds
5	High Temperature Exposure	△L<10%	JIS-C-5202-7.2 85±2°C, 1000 +48/-0 hours
6	Moisture Resistance	△L<10%	MIL-STD-202F Method 103B 40±2°C, 90~95%RH, 1000 +48/-0 hours
7	Low Temperature Storage	△L<10%	JIS-C-5202-7.1 -40±3°C, 1000 +48/-0 hours
8	Temperature Cycle	△L<10%	JIS-C-5202-7.4 -40/RT/85/RT, 10 cycles
9	Solderability	95% min coverage	MIL-STD-202F Method 208H 245°C ±5°C,3±0.5(sec)

Mfr PN	Inductance	Inductance Tolerance	DC Resistance Max	DC Current Rating	Self Resonant Frequency	Package/ Case	Q Factor	Test Frequency
MCFT000011	1nH	±0.1 nH	0.35ohm	800mA	13GHz	603	Q Factor:15	300MHz
MCFT000012	1.5nH	±0.1 nH	0.35ohm	800mA	10GHz	603	Q Factor:15	300MHz
MCFT000013	2.2nH	±0.1 nH	0.35ohm	300mA	8GHz	603	Q Factor:15	300MHz
MCFT000014	3.3nH	±0.1 nH	0.45ohm	300mA	6GHz	603	Q Factor:15	300MHz
MCFT000015	4.7nH	±0.1 nH	0.55ohm	300mA	5GHz	603	Q Factor:15	300MHz
MCFT000016	6.8nH	±0.1 nH	0.75ohm	300mA	5GHz	603	Q Factor:15	300MHz
MCFT000017	10nH	±1%	0.95ohm	300mA	4GHz	603	Q Factor:15	300MHz
MCFT000018	15nH	±1%	1.35ohm	300mA	3GHz	603	Q Factor:15	300MHz
MCFT000019	22nH	±1%	1.95ohm	250mA	2GHz	603	Q Factor:15	300MHz
MCFT000020	33nH	±1%	2.75ohm	250mA	1.5GHz	603	Q Factor:15	300MHz
MCFT000021	47nH	±1%	3ohm	200mA	1.5GHz	603	Q Factor:15	300MHz
MCFT000022	68nH	±1%	5ohm	150mA	1GHz	603	Q Factor:15	300MHz
MCFT000023	100nH	± 2%	7.5ohm	100mA	1GHz	603	Q Factor:15	300MHz

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SCALE: NTS | U.O.M.: INCHES [mm] | SHEET: 2 OF 2